SZCJ

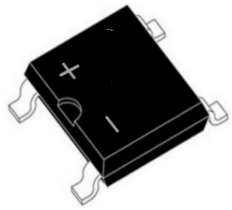
ABS Plastic-Encapsulate Bridge Rectifier

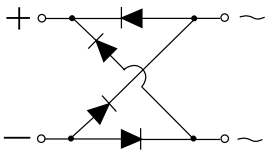
RABS210Z Fast Recovery Bridge Rectifier

Features

- $I_{F(AV)}$ 2A
- V_{RRM} 1000V
- High surge current capability
- Glass passivated chip

ABS





Applications

- General purpose 1 phase Bridge rectifier applications

Marking

- RABS210Z

Limiting Values (Absolute Maximum Rating)

Item	Symbol	Unit	Conditions		RABS210Z
Repetitive Peak Reverse Voltage	V_{RRM}	V			1000
Maximum RMS Voltage	V_{RMS}	V			700
Maximum DC Blocking Voltage	V_{DC}	V			1000
Average Rectified Output Current	I_O	A	60Hz sine wave, R-load,Ta=60℃	On alumina substrate	2.0
Surge(Non-repetitive)Forward Current	I_{FSM}	A	8.3ms half sine wave, 1 cycle, T_j=25℃		60
Current Squared Time	I^2t	A^2S	t=8.3ms Tj=25℃， Rating of per diode		14.94
Operation Junction and Storage Temperature Range	T_J,T_{stg}	℃			-55 ~+150

Electrical Characteristics (T=25℃ Unless otherwise specified)

Item	Symbol	Unit	Test Condition	RABS210Z
Maximum Peak Forward Voltage	V_{FM}	V	I_{FM}=2.0A, Pulse measurement, Rating of per diode	1.3
Maximum Peak Reverse Current	I_{RRM}	μA	V_{RM}=V_{RRM} , Pulse measurement, Rating of per diode	5
MaximumPeak Reverse Current	trr	ns	I_F=0.5A,I_R=1.0A,Irr=0.25A	500
Thermal Resistance	$R_{\theta J-A}$	℃/W	Between junction and ambient, On alumina substrate	108
	$R_{\theta J-L}$		Between junction and lead	25
	$R_{\theta J-C}$		Between junction and case	20
Juction Capacitance (Typical)	Cj	pF	Measured at 1MHZ and Applied Reverse Voltage of 4.0 V.D.C.	15

Notes: Thermal resistance from junction to ambient, from junction to lead mounted and from junction to case mounted on 1" x 1" (25.4mm x 25.4mm) FR4 PCB, double sided copper, with minimum pad layout

Typical Characteristics

FIG.1:FORWARD CURRENT DERATING CURVE

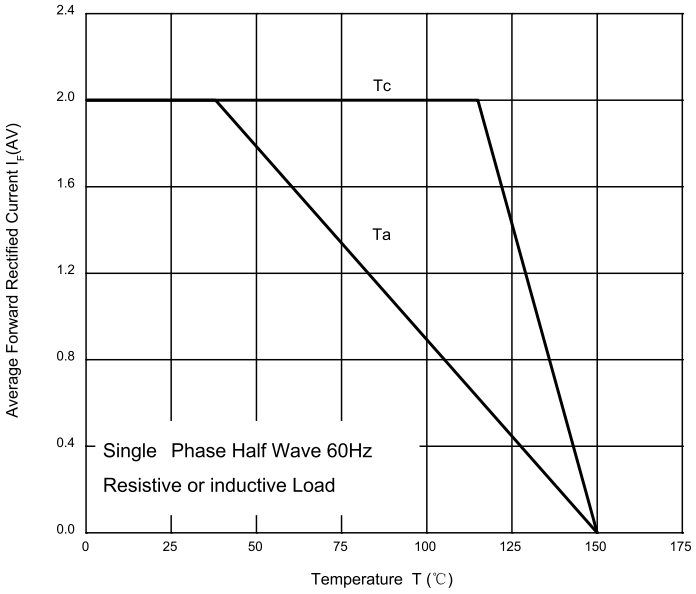


FIG.2: MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

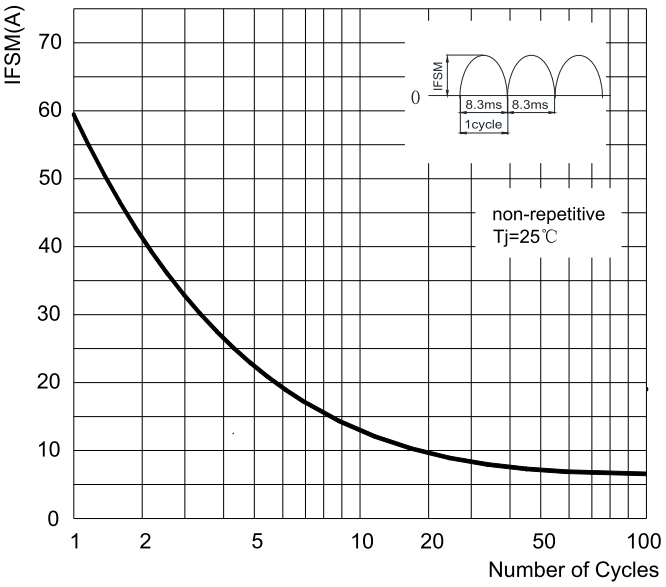


FIG.3: TYPICAL FORWARD CHARACTERISTICS

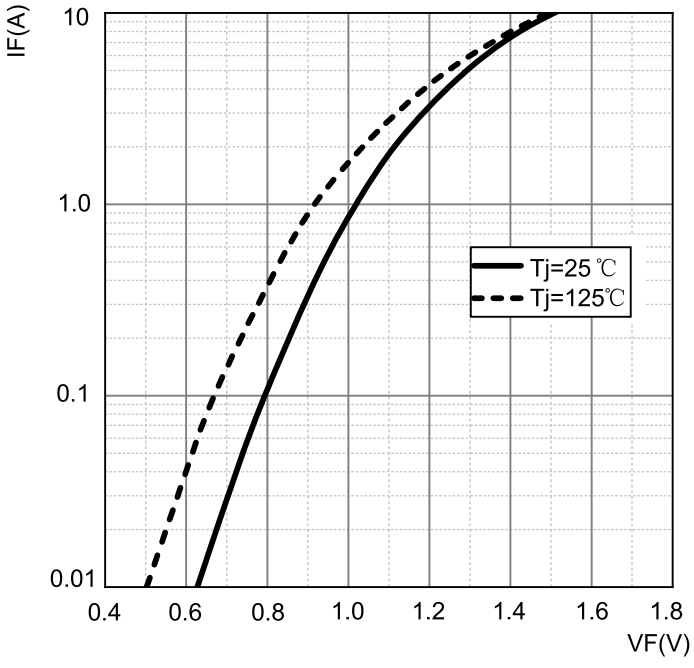
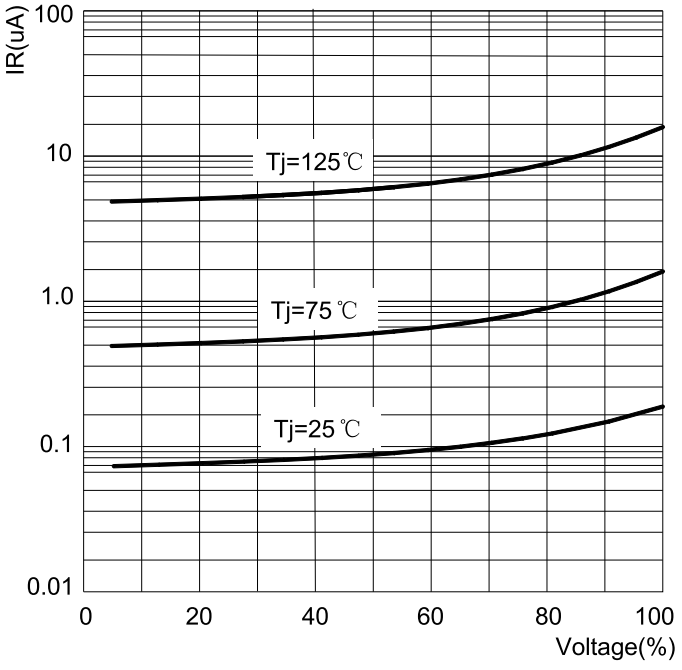
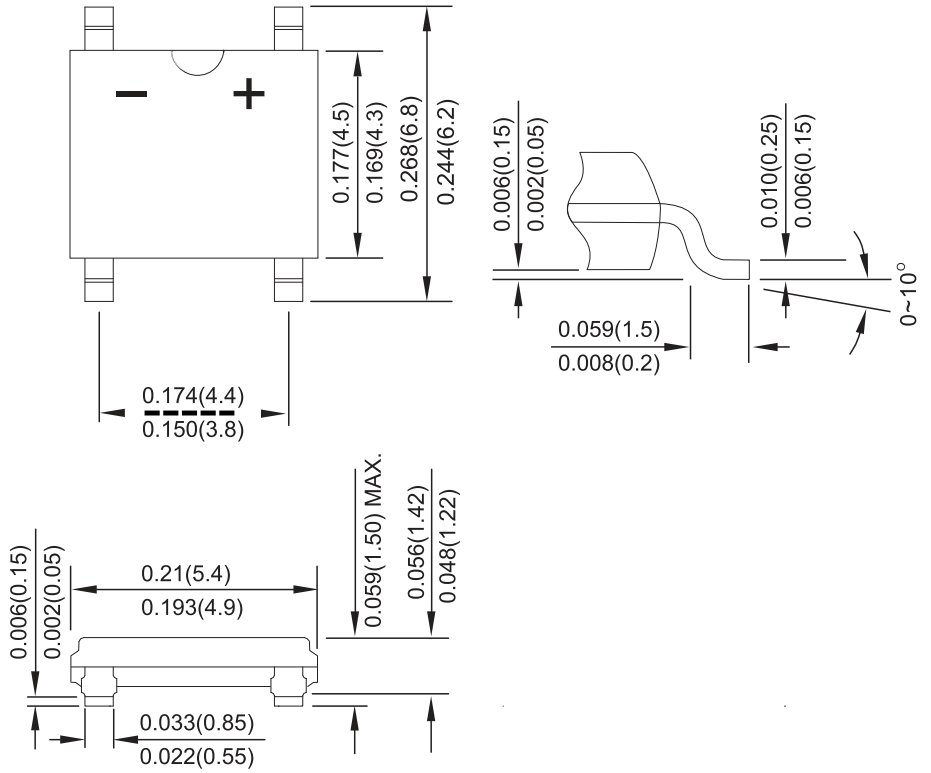


FIG.4:TYPICAL REVERSE CHARACTERISTICS

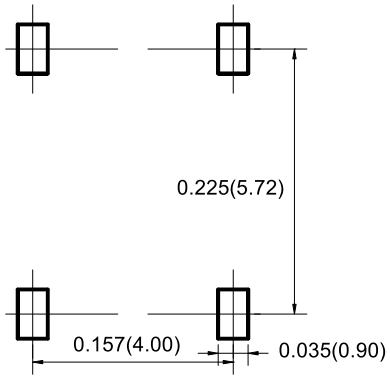


ABS Package Outline Dimensions



Dimensions in inches and (millimeters)

ABS Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

NOTICE

JSCJ reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein.JSCJ does not assume any liability arising out of the application or use of any product described herein.

Reel Taping Specifications For Surface Mount Devices-ABS

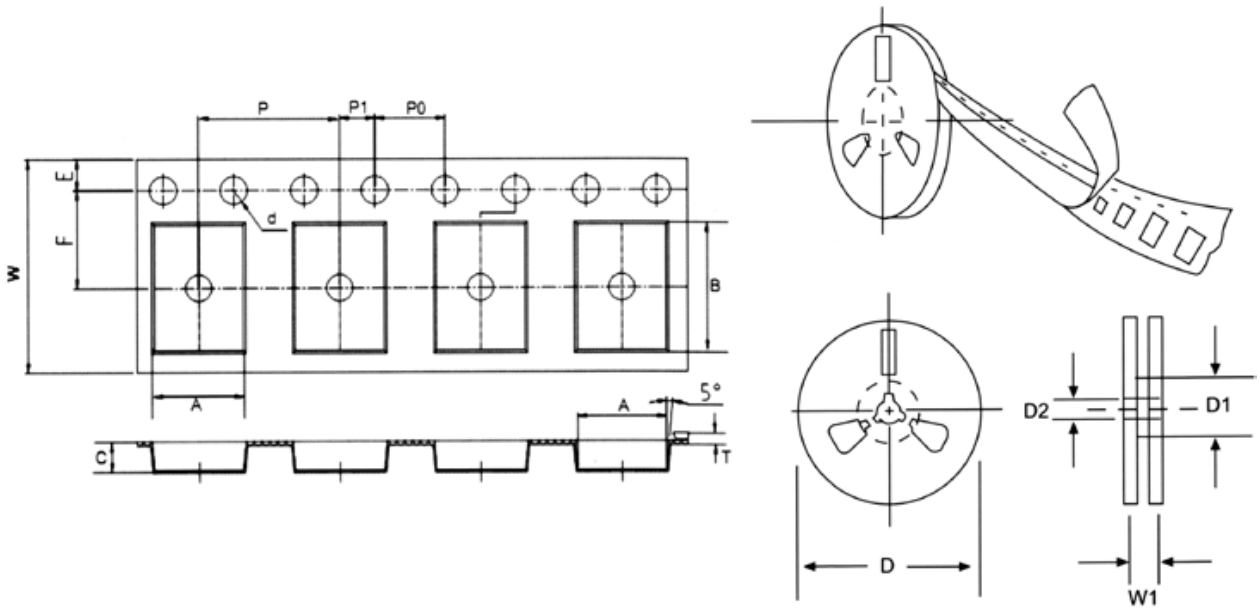


FIG:CONFIGURATION OF SURFACE MOUNTED DEVICES TAPING

ITEM	SYMBOL	ABS mm(inch)
Carrier width	A	5.40+0.1(0.213+0.004)
Carrier length	B	6.90+0.05(0.272+0.002)
Carrier depth	C	2.10+0.1(0.083+0.004)
Sprocket hole	d	1.55±0.05(0.061±0.002)
Reel outside diameter	D	279±2.0 (11± 0.079)
Reel inner diameter	D1	75 ±1.0 (2.95 ±0.039)
Feed hole diameter	D2	13+0.5(0.512+0.020)
Stroket hole position	E	1.75+0.1(0.069+0.004)
Punch hole position	F	5.5+0.05(0.217+0.002)
Punch hole pitch	P	8.0+0.1(0.315+0.004)
Sprocket hole pitch	P0	4.0+0.1(0.157+0.004)
Embossment center	P1	2.0+0.1(0.079+0.004)
Totall tape thickness	T	0.10-0.70(0.004-0.028)
Tape width	W	12.0+0.3/-0.1(0.472+0.004)
Reel width	W1	16.8+2.0(0.661+0.079)

NOTE:Devices are packde in accordance with EIA standard RS-481-A and specification given above.